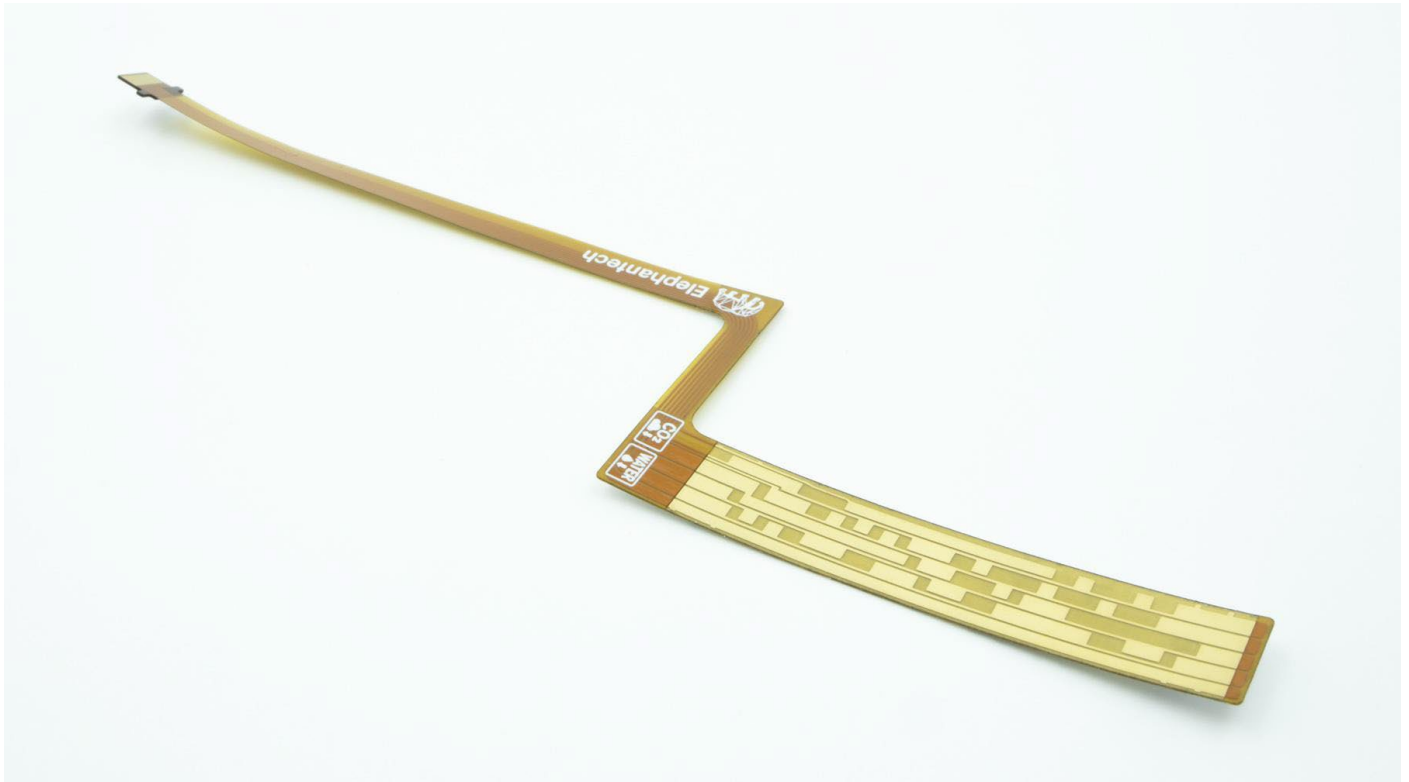


## Electrolytic Gold-plated Surface P-Flex® PI Samples Now Available

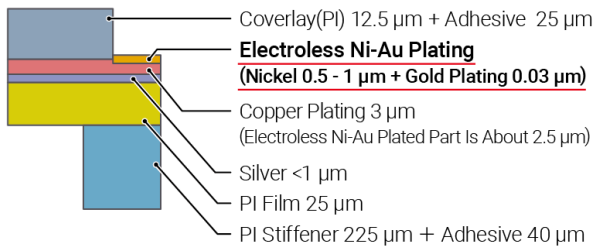
Elephantech Inc. (headquarters: Chuo-ku, Tokyo, CEO: Shinya Shimizu, hereinafter “Elephantech”) is pleased to announce that it has begun offering samples of P-Flex® PI with electrolytic gold plating surface treatment.



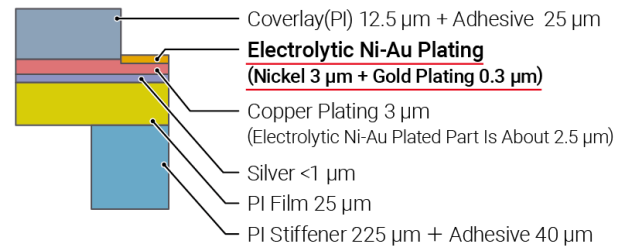
Newly added to the lineup: P-Flex® PI with electrolytic gold-plated surface treatment

Elephantech mass-produces P-Flex®, a Flex PCB based on inkjet printing technology which has the advantages of low environmental impact, flexible prototyping and mass production, and high cost competitiveness. We have been offering two types of surface treatment for P-Flex®: electroless gold plating and antioxidant treatment. While the thin surface film thickness of electroless gold plating and antioxidant treatment can reduce production costs with regards to the recent rise in metal prices, they have the disadvantage of being inferior in wear resistance. In response to many customers' requests, we are now offering samples of P-Flex® PI with electrolytic gold plating surface treatment. While electroless gold plating requires a gold thickness of 0.03 $\mu$ m or more, electrolytic gold plating enables a thickness of 0.3 $\mu$ m or more, a 10-fold increase.

This is expected to improve the abrasion resistance of the gold plating layer when connectors are inserted and removed, and improve corrosion resistance by reducing exposure of the underlying nickel layer and copper foil.

**P-Flex® PI specifications for each surface treatment**
**Electroless Ni-Au Plating Specifications**


Connector Part Total Thickness 293 μm (300 μm ±50 μm)

**Electrolytic Ni-Au Plating Specifications**


Connector Part Total Thickness 295.8 μm (300 μm ±50 μm)

We are constantly working on increasing our product lineup so that P-Flex® PI can be used by an ever increasing number of customers, so please feel free to contact [our P-Flex Sales Department](#) or [our distributors](#) for more information or clarification on upcoming products.

With a mission to "Making the world sustainable with new manufacturing technologies", we spare no effort in our attempts to make any little contribution to the development of the electronics industry, and we are truly grateful for the continued support and interest we receive as none of this would be possible without it.

**Company Overview**

Name	Elephantech Inc.
Establishment	January 2014
Headquarters	4-3-8 Hatchobori, Chuo-ku, Tokyo 104-0032, Japan
Representative	Shinya Shimizu, CEO
Capital	JPY 100 million
Number of employees	74
Business description	Development of printed electronics manufacturing technology and provision of related services
URL	<a href="https://www.elephantech.co.jp/en/">https://www.elephantech.co.jp/en/</a>

As of May 1, 2022

Contact for inquiries regarding this matter  
 Elephantech Inc. Public Relations [pr@elephantech.co.jp](mailto:pr@elephantech.co.jp)